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CONVEYING PARTY(IES): (Last name first)

Hideshi Hanada
Jun Sugimoto
Yuichi Douki

Execution Date
6/19/01
6/20/01
6/19/01

Mark if additional names of conveying parties attached

RECEIVING PARTY:

Name: Mitsui High-tec Inc.
Address: 10-1, Komine 2 chome,
Yahatanishi-ku
City: Kitakyushu 806-8588
Country: Japan
Zip Code:

Mark if additional names of receiving parties attached

APPLICATION NUMBER(S) OR PATENT NUMBER(S)

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Enter either the Patent Application Number or the Patent Number (DO NOT ENTER BOTH numbers for the same property).

If this document is being filed together with a new Patent Application, enter the date the patent application was signed by the first named inventor: 00/00/00

Patent Application Number(s):

09/878,637

Patent Number(s):

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CORRESPONDENT NAME AND ADDRESS:

Wood, Phillips, Katz, Clark & Mortimer
Citicorp Center, Suite 3800
500 West Madison Street
Chicago, Illinois 60661-2511
(312) 876-1800

FEE AMOUNT:

Total Fee (37 CFR 3.41) \$40.00

Enclosed
 Charge to Deposit Account 23-0785
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STATEMENT AND SIGNATURE

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Charges to deposit account are authorized, as herein indicated.

11/18/2002 6TON11 00000141 230785 09878637

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John S. Mortimer

Name of Person Signing

Signature

10/21/02

PATENT Date

REEL: 013494 FRAME: 0301

A S S I G N M E N T

Serial No. 09/878,637

Filed 6/11/01

In consideration of One Dollar and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned inventor, or each inventor if more than one, hereby assigns to Mitsui High-tec Inc. (a Japanese corporation)

its successors and assigns (hereinafter called "said assignee"), the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, entitled, SEMICONDUCTOR DEVICE AND LEAD FRAME ASSEMBLY/LEAD FRAME FOR MAKING A SEMIDONCUTRO DEVICE

executed by the undersigned on the ~~20th~~^{19th} day of June, 2001, and in said application and any and all other applications for United States Letters Patent, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents to issue said Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the date and serial number of said application.

For said consideration, the undersigned hereby agrees, upon the request and at the expense of said assignee, to execute any divisional, continuation or substitute application for said invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, and, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof. The undersigned agrees to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and vest in said assignee all rights therein, whereby said Letters Patent will be held and enjoyed by said assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same should have been held and enjoyed by the undersigned if this assignment had not been made.

And for said consideration, the undersigned hereby assigns to said assignee the entire right, title and interest in said invention or improvements for all foreign countries, including all priority rights under

the International Convention, and agrees to execute, at the request of said assignee, all documents in connection with any application for foreign letters patent therefor.

H. Hanada 6/19/01
HIDESHI HANADA

J. Sugimoto 6/20/01
JUN SUGIMOTO

Y. Douki 6/19/01
YUICHI DOUKI

_____, 20____
STATE OF _____
COUNTY OF _____

Before me, a Notary Public in and for the County and State aforesaid, appeared _____

_____ to me personally known to be the signer, or signers, of the foregoing instrument, and acknowledged execution of said instrument as a free and voluntary act for the uses and purposes therein expressed.

Notary Public

WOOD, PHILLIPS, VanSANTEN, CLARK & MORTIMER
500 West Madison Street, Suite 3800
Chicago, Illinois 60661-2511